FORM PTO-1595 (Modified)

05 (17/20)

-ADMC 01 00000012 108479.3

A.

(Rev. 03-01) OMB No. 0651-0027 (exp.5/31/2002) P08A/REV03



102774873

Docket No.: XA-10114

ΕT

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

Tab settings → → ▼	⁷⁷³ ▼
To the Director of the United States Patent and Trademark Off	ice: Please record the attached original documents or copy thereof.
1. Name of conveying party(ies): Naoki YADA Mitsuhiko OKUTSU Yasuyuki SAITO	Name and address of receiving party(ies): Name and address of receiving party(ies):
Yasushi SHIBATSUKA 6.15.64 Katsunori KOIKE	Name: Renesas Technology Corp. Address: 4-1, Marunouchi 2-chome
Additional names(s) of conveying party(ies)	N867
3. Nature of conveyance: ☑ Assignment □ Merger	
☐ Security Agreement ☐ Change of Name	City: Chiyoda-ku State/Prov.: Tokyo
☐ Other	Country: Japan ZIP:
Execution Date: April 1, 1, 5, 5, and 5, 2004	Additional name(s) & address(es) ☑ Yes ☐ No
Additional numbers	☐ Yes ☐ No
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Mitchell W. Shapiro	7. Total fee (37 CFR 3.41):\$ 40.00
Registration No. 31,568 Address: Miles & Stockbridge P.C.	Enclosed - Any excess or insufficiency should be credited or debited to deposit account
1751 Pinnacle Drive	☐ Authorized to be charged to deposit account
Suite 500	8. Deposit account number:
City: McLean State/Prov.: Virginia	50-1165
Country: <u>U.S.</u> <u>ZIP: 22102</u>	(Attach duplicate copy of this page if paying by deposit account)
Statement and signature.	ation is true and correct and any attached copy is a true copy
Mitchell W. Shapiro	June 15, 2004
Name of Person Signing	Signature Date

Total number of pages including cover sheet, attachments, and

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services

Director of the United States Patent and Trademark Office

P.O. Roy 1450 Aleyandria VA 22313-1450

PATENT

REEL: 015481 FRAME: 0753

FORM PTO-1619A **U.S. Department of Commerce** Expires 06/30/99 Patent and Trademark Office OMB 0651-0027 **PATENT** RECORDATION FORM COVER SHEET PATENTS ONLY TO: The Commissioner of Patents and Trademarks: Please record the attached original document(s) or copy(ies) Submission Type Conveyance Type New **Assignment Security Agreement Resubmission (Non-Recordation)** License **Change of Name Document ID#** Correction of PTO Error Merger Other Reel# Frame # U.S. Government Corrective Document (For Use ONLY by U.S. Government Agencies) Reel# Frame # Departmental File **Secret File** Mark if additional names of conveying parties attached Execution Date Conveying Party(ies) Day Year Name (line 1) Name (line 2) Second Party **Execution Date** Month Day Name (line 1) Name (line 2) Receiving Party Mark if additional names of receiving parties attached Name (line 1) Hitachi Engineering Co., Ltd. If document to be recorded is an assignment and the receiving party is not domiciled in the United Name (line 2) States, an appointment of a domestic representative is attached. Address (line 1) 2-1, Saiwaicho 3-chome (Designation must be a separate document from Assianment.) Address (line 2) Hitachi-shi Address (line 3) Ibaraki Japan State/Country Zip Code **Domestic Representative Name and Address** Enter for the first Receiving Party only. Name Address (line 1) Address (line 2) Address (line 3) Address (line 4) FOR OFFICE USE ONLY

Public burden reporting for this collection of information is estimated to average approximately 30 minutes per Cover Sheet to be recorded, including time for reviewing the document and gathering the data needed to complete the Cover Sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Chief Information Officer, Washington,

D.C. 20231 and to the Office of Information and Regulatory Affairs, Office of Management and Budget, Paperwork Reduction Project (0651-0027), Washington, D.C. 20503. See OMB

Mail documents to be recorded with required cover sheet(s) information to:

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp.,

and Hitachi Engineering Co., Ltd.

corporations organized under the laws of Japan,

located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan,

and 2-1, Saiwaicho 3-chome, Hitachi-shi., Ibaraki , Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., and Hitachi Engineering Co., Ltd.

their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Paten which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., and Hitachi Engineering Co., Ltd.

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp., and Hitachi Engineering Co., Ltd.

Signed on the date(s) indicated aside our signatures:

RECORDED: 06/15/2004

INVENTOR(S)	Date Signed
(発明者フルネームサイン)	(署名日)
1) <u>Raoki Bada Naoki YADA</u>	1 / Apil / 2004 24 / Mag/ N.Y
1) Raoki Yada Naoki YADA 2) Yasayaki Saito Yasuyuki SAITO	1/Api/1/2004 24/May/2004 Y.S
3) Vasushi Shibatsukarasushi SHIBATS	SUKA 5 /April /2004
4) Katsunori Koike Katsunori KOIKE	
5) Mitsuhiko Chutsu Mitsuhiko OKUTS	su <u>5 / April / 2004</u>
6)	
7)	
8)	
9)	
10)	
\	

PATENT REEL: 015481 FRAME: 0755